

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT4455095

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	CONG ZHANG	05/17/2017
	FUQIANG XIAO	05/17/2017
	BIN XU	05/22/2017
	HAIJUN WU	05/18/2017
	CHIN TIEN CHIU	05/17/2017
	ZENGYU ZHOU	05/17/2017
RECEIVING PARTY DATA		
Name:	SANDISK INFORMATION TECHNOLOGY (SHANGHAI) CO., LTD.	
Street Address:	NO. 388, JIANG CHUAN EAST ROAD	
Internal Address:	MINHANG DISTRICT	
City:	SHANGHAI	
State/Country:	CHINA	
Postal Code:	200241	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	15619895
CORRESPONDENCE DATA		
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
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ATTORNEY DOCKET NUMBER:	SAND-01961US0	
NAME OF SUBMITTER:	BRIAN I. MARCUS	
SIGNATURE:	/Brian I. Marcus/	
DATE SIGNED:	06/12/2017	

Total Attachments: 7

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JOINT TO CORPORATE ASSIGNMENT

WHEREAS, the undersigned Inventors:

- (1) Cong Zhang, a resident of Shanghai, China;
- (2) Fuqiang Xiao, a resident of Shanghai, China;
- (3) Bin Xu, a resident of Shanghai, China;
- (4) Haijun Wu, a resident of Shanghai, China;
- (5) Chin Tien Chiu, a resident of Taichung City, Taiwan; and
- (6) Zengyu Zhou, a resident of Shanghai, China,

have invented certain new and useful improvements in:

A FAN OUT SEMICONDUCTOR DEVICE INCLUDING A PLURALITY OF SEMICONDUCTOR DIE

and have executed a declaration for an application for a United States Patent disclosing and identifying the invention, the declaration being executed on 5/17/17; 5/17/17; 5/22/17; 5/18/17; 5/17/17; 5/17/17.

WHEREAS SANDISK INFORMATION TECHNOLOGY (SHANGHAI) CO., LTD. (hereinafter termed "Assignee"), a Chinese corporation having a place of business at No. 388, Jiang Chuan East Road, Minhang District, Shanghai 200241, China, wishes to acquire the entire right, title and interest in and to said application and the invention disclosed therein, and in and to all embodiments of the invention, heretofore conceived, made or discovered jointly or severally by said Inventors (all collectively hereinafter termed "said invention"), and in and to any and all patents, certificates of invention and other forms of protection thereon (hereinafter termed "patents") applied for or granted in the United States and/or other countries.

NOW THEREFORE, for good and valuable consideration acknowledged by each of said Inventors to have been received in full from said Assignee:

1. Said Inventors do hereby sell, assign, transfer and convey to said Assignee, the entire right, title and interest (a) in and to said application and said invention; (b) in and to all rights to apply in any or all countries of the world for patents, certificates of inventions or other governmental grants on said invention, including the right to apply for patents pursuant to the International Convention for the Protection of Industrial Property or pursuant to any other convention, treaty, agreement or understanding; (c) in and to any and all applications filed and any and all patents, certificates of inventions or other governmental grants granted on said invention in the United States or any other country, including each and every application filed and each and

every patent granted on any application which is a division, substitution, or continuation of any of said applications; (d) in and to each and every reissue or extension of any of said patents; and (e) in and to each and every patent claim resulting from a reexamination certificate for any and all of said patents.

2. Said Inventors hereby jointly and severally covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest herein conveyed in the United States and other countries. Such cooperation by said Inventors shall include prompt production of pertinent facts and documents, giving of testimony, executing of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for complying with any duty of disclosure; (c) for prosecuting any of said applications; (d) for filing and prosecuting substitute, divisional, continuing or additional applications covering said invention; (e) for filing and prosecuting applications for reissue of any of said patents; (f) for interference or other priority proceedings involving said invention; and (g) for legal proceedings involving said invention and any applications therefor and any patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, reexamination proceedings, compulsory licensing proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Inventors in providing such cooperation shall be paid for by said Assignee.

3. The terms and covenants of this Assignment shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Inventors, their respective heirs, legal representatives and assigns.


4. Said Inventors hereby jointly and severally warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

Date: May. 17/2017 (1) Cong Zhang
Cong Zhang

Date: May 17, 2017

(2) Fuqiang Xiao
Fuqiang Xiao

Date: 2017.5.22

(3) 
Bin Xu

Date: 2017.05.18

(4) Haijun Wu
Haijun Wu

Date: May 17 '17

(s) Chin Tien Chiu
Chin Tien Chiu

Date: 2017.5.17

(6) Zengyu Zhou
Zengyu Zhou